Philips Components

Data sheet	
status	Product specification
date of issue	October 1990

2N7000
N-channel enhancement mode vertical D-MOS transistor

FEATURES

- Low $R_{DS(on)}$
- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

DESCRIPTION

N-channel enhancement mode vertical D-MOS transistor in a TO-92 variant envelope, intended for use in relay, high-speed and line transformer drivers.

PINNING - TO-92 variant

PIN	DESCRIPTION
1	drain
2	gate
3	source

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_{DS}	drain-source voltage		60	V
I_D	drain current	DC value	280	mA
$R_{DS(on)}$	drain-source on-resistance	I_D = 500 mA V_{GS} = 10 V	5	Ω
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA V_{GS} = V_{DS}	3	V

PIN CONFIGURATION

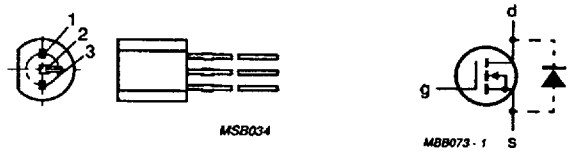

Fig.1 Simplified outline and symbol.

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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage		–	60	V
V_{DG}	drain-gate voltage		–	60	V
$\pm V_{GSO}$	gate-source voltage	open drain	–	40	V
I_D	drain current	DC value	–	280	mA
I_{DM}	drain current	peak value	–	1.3	A
P_{tot}	total power dissipation	T_{amb} = 25 °C	–	830	mW
T_{stg}	storage temperature range		–55	150	°C
T_j	junction temperature		–	150	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j\text{-}a}$	from junction to ambient	150	K/W

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CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 10 µA V_{GS} = 0	60	90	–	V
I_{DSS}	drain-source leakage current	V_{DS} = 48 V V_{GS} = 0	–	–	1	µA
$\pm I_{GSS}$	gate-source leakage current	$\pm V_{GS}$ = 15 V V_{DS} = 0	–	–	10	nA
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA V_{GS} = V_{DS}	0.8	–	3	V
$R_{DS(on)}$	drain-source on-resistance	I_D = 500 mA V_{GS} = 10 V	–	2.5	5	Ω
		I_D = 75 mA V_{GS} = 4.5 V	–	–	5.3	Ω
$\|Y_{fs}\|$	transfer admittance	I_D = 200 mA V_{DS} = 10 V	100	200	–	mS
C_{iss}	input capacitance	V_{DS} = 10 V V_{GS} = 0 f = 1 MHz	–	25	40	pF
C_{oss}	output capacitance	V_{DS} = 10 V V_{GS} = 0 f = 1 MHz	–	22	30	pF
C_{rss}	feedback capacitance	V_{DS} = 10 V V_{GS} = 0 f = 1 MHz	–	6	10	pF
Switching times (see Figs 2 and 3)						
t_{on}	turn-on time	I_D = 200 mA V_{DD} = 50 V V_{GS} = 0 to 10 V	–	4	10	ns
t_{off}	turn-off time	I_D = 200 mA V_{DD} = 50 V V_{GS} = 0 to 10 V	–	4	10	ns

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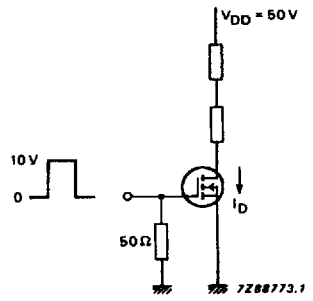

Fig.2 Switching time test circuit.

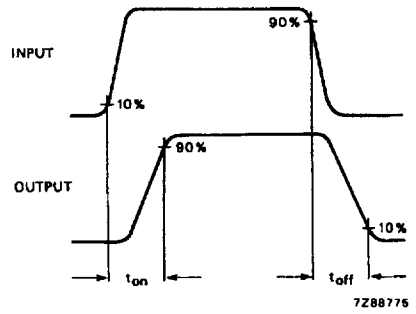

Fig.3 Input and output waveforms.

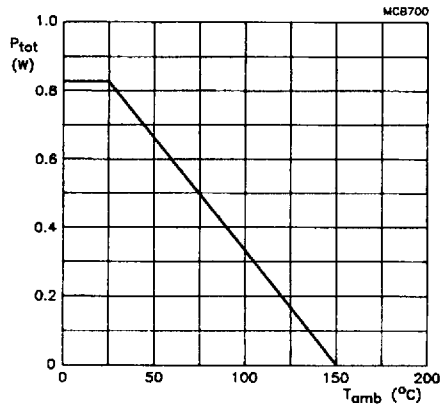

Fig.4 Power derating curve.

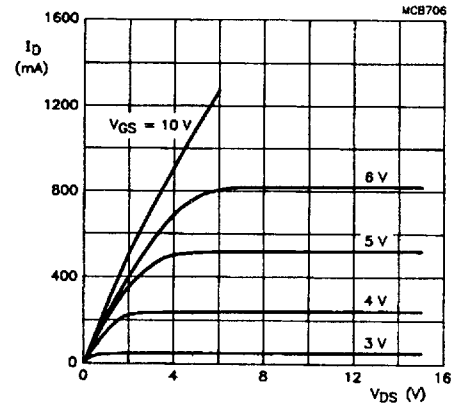

Fig.5 Typical output characteristics; T_j = 25 °C.

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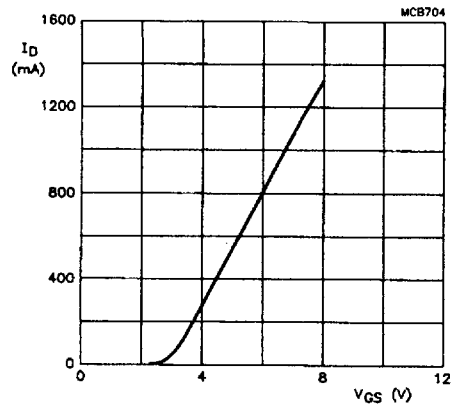

Fig.6 Typical transfer characteristic; V_{DS} = 10 V; T_j = 25 °C.

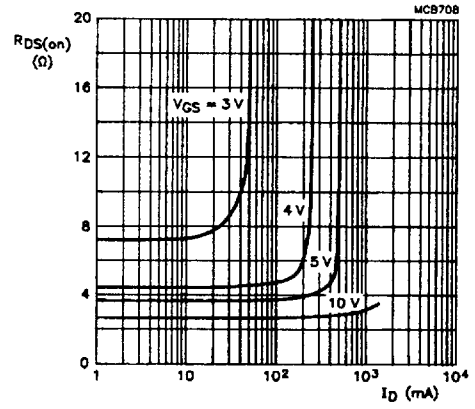

Fig.7 Typical on-resistance as a function of drain current; T_j = 25 °C.

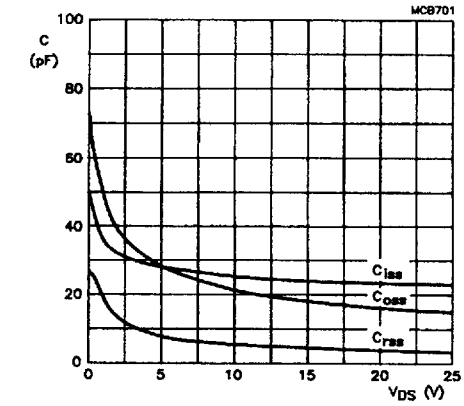

Fig.8 Typical capacitances as a function of drain-source voltage; V_{GS} = 0; f = 1 MHz; T_j = 25 °C.

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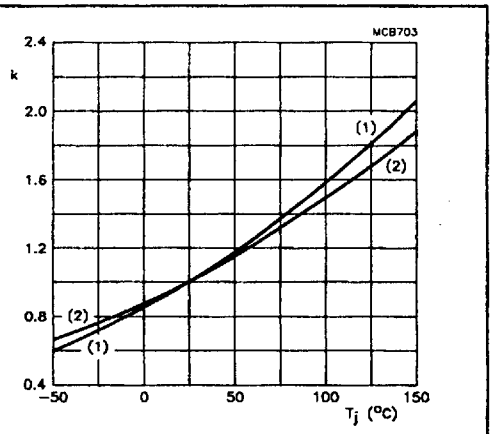

(1) I_D = 500 mA; V_{GS} = 10 V.
(2) I_D = 75 mA; V_{GS} = 4.5 V.

Fig.9 Temperature coefficient of drain-source on-resistance; $k = \frac{R_{DS(on)} \text{ at } T_j}{R_{DS(on)} \text{ at } 25\,°C}$; typical $R_{DS(on)}$.

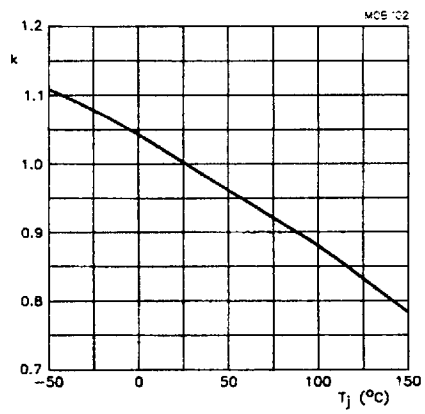

Fig.10 Temperature coefficient of gate-source threshold voltage; $k = \frac{V_{GS(th)} \text{ at } T_j}{V_{GS(th)} \text{ at } 25\,°C}$; typical $V_{GS(th)}$ at 1 mA.

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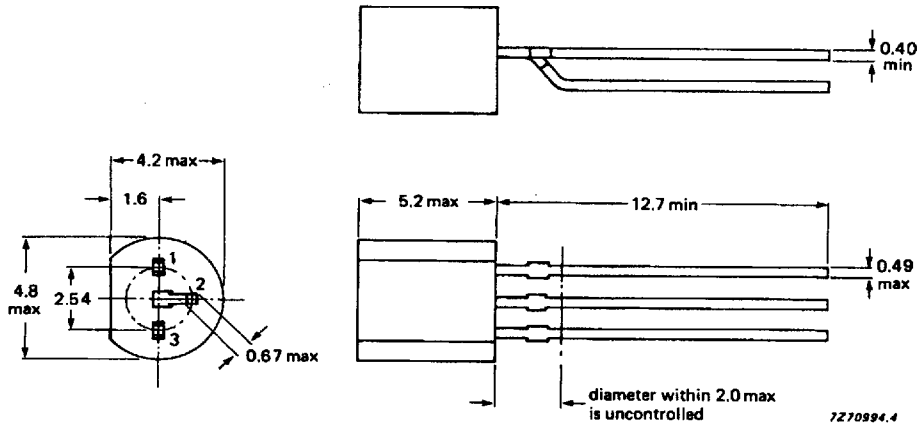
PACKAGE OUTLINE



Dimensions in mm.

Fig.11 TO-92 variant.